广东东溢新材料科技有限公司 GUANGDONG DONGYI HIGH-TECH MATERIAL SCIENCE&TECHNOLOGY CO., LTD.

# 品质承认书 Quality specification

	客户 Customer:		7-					
	供应商:广东东溢新材料	科技有限公司						
	Supplier: GUANGDONG DONG	GYI HIGH-TECH MATERIAL SC	IENCE&TECHNOLOGY CO., LTD.					
	产品类型 Product type: 月 Free stiffener	F.卤环氧有胶黑色补强板	Black PI Base Epoxy Halogen					
	材料品名 Material name:	DTIB 黑色补强板系列						
	编号 No: T64 版本 V	er: A4						
	制作日期 Date of production	on:2024/04/11						
	客户确认 Customer:		YYX					
	采购 Purchase:	品质 Quality:	工程 Engineering:					
	职务 Position:	职务 Position:	职务 Position:					
	备注 Note: (盖章 Seal)		X					
广东东溢新材料科技有限公司 GUANGDONG DONGYI HIGH-TECH MATERIAL SCIENCE&TECHNOLOGY CO., LTD.								
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# 产品名称 Product name

序号	东溢型号	PI 厚度	胶厚	包装
No	DY models	(mil)	(um)	Packing
1	DTIB125NB1 (A)	1	25	250mm*200m
2	DTIB225NB1(A)	2	25	250mm*100m
3	DTIB325NB1	3	25	250mm*100m
4	DTIB325NB1 (B)	3	25	250mm*100m
5	DTIB330NB1 (B)	3	25	250mm*100m
6	DTIB425NB1	4	25	250mm*100m
7	DTIB425NB1 (B)	4	25	250mm*100m
8	DTIB525NB1	5	25	250mm*100m
9	DT1B525NB1 (B)	5	25	250mm*100m
10	DTIB625NB1	6	25	250mm*50m
11	DTIB625NB1 (B)	6	25	250mm*50m
12	DTIB725NB1	7	25	250mm*50m
13	DTIB725NB1 (B)	7	25	250mm*50m
14	DTIB725NB1(C)	7	25	250mm*50m
15	DTIB825NB1	8	25	250mm*50m
16	DTIB825NB1(B)	8	25	250mm*50m
17	DTIB825NB1(C)	8	25	250mm*50m
18	DTIB925NB1	9	25	250mm*50m
19	DTIB925NB1 (B)	9	25	250mm*50m

# ●产品特性 Product Features

- ■优秀的耐热性能 Outstanding thermal resistance
- ■优异的平坦性 Excellent flatness
- ■优良的耐化学性 Good chemical resistance
- ■优异的电性能 Excellent electrical performance and insulation performance
- 无卤无锑, 符合 ROHS 环保指令 Halogen & antimony free, ROHS compliant

## ●产品结构 Product Structure

PI膜 PI film 环氧胶粘剂 Epoxy Adhesive 离型膜 Release PET



# ●物性指标 General Properties

序号 Item	性能项目 Test Item	单位 Unit	测试条件 Test Condition	标准 Standard	测试方法 Test Method
1	厚度 Thickness	um	厚度≤100um	$\pm$ 5um	东溢规范 Dongyi
1	序/支 THICKNESS	um	厚度>100um	$\pm 10\%$	Method
2	幅宽 Width			标准值	东溢规范 Dongyi
Z	悝见 Wiuui	mm	A	+2/-0mm	Method
3	剥离强度 Peel Strength	kgf/cm	A	≥1.0	IPC-TM-650-2.4.9
4	焊锡耐热性 Solder Resistance		288°C/10S	无分层、起泡 No delamination, sparkling	IPC-TM-650-2.4.13
5	溢胶量 Resin Flow	mm	180°C/10s /100kgf/90s	0.05~0.30	IPC-TM-650-2.3.17.1
6	翘曲 Curl	cm	А	≤5	IPC-TM-650-2.3.17.1



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7	表面电阻 Surface Resistance	Ω	C-96/23/65	$\geq 10^{10}$	IPC-TM-650-2.5.17
8	体积电阻 Volume Resistance	Ω.cm	C-96/23/65	$\geq 10^{12}$	IPC-TM-650-2.5.17
9	介电常数 Dielectric Constant		C-24/23/50 (10MHz)	≦4.0	IPC-TM-650-2.5.5.3
10	消耗因素 Dissipation Factor		C-24/23/50 (10MHz)	≦0.04	IPC-TM-650-2.5.5.3

注 Note: A 代表常态"A" Means normal。

# ● 外观管控 Appearance requirement

异常类型 Exception classes	异常大小 Abnormal size 允	2许个数Allowed value(250*400mm)
杂质 Impurity	$0.1^{\sim}0.5$ m	m ≦8个dots
垫伤 Pad injury	0. 5~1mm	≦1个 dots
气泡 Bubble	≧1mm 不	允许Not allowed
接头 Joint	S	≦3个

注Note: 产品边缘 3mm 以内异常, 不作管控要求 From the product within 3 mm of the edge of exception, don't do control requirements。

## ● 储存 Storage

1. 环氧有胶补强板: 温度<10℃、湿度<70%RH、真空包装、无腐蚀性气体的室内,制造日期后保存3个月。Temperature <10℃, humidity < 70% RH, airproof

vacuumed packaging, no corrosive gas chamber for 3 months.

2. 产品开封后,常温储存,温度 15~30℃、湿度 40~70% RH,储存周期 7 天。 After the product is opened, storage at room temperature, Temperature 15<sup>°</sup>30℃, humidity 40<sup>°</sup>70% RH, Storage time for 7 days (储存周期是指产品从开封到压合 固化前整个过程。Storage cycle refers to the whole process of the product from unpacking to pressing and curing)。

# )包装 Packing

1. 每一卷成品用 PVC 卷取。每批出货的每个规格提供一份品质检验报告。Each volume of finished PVC tube winding。

2. 每一卷成品用纸箱包装,避免在运输上碰撞。产品采用防潮、干燥、密封包装,成卷装入纸箱。Each volume of finished carton packaging, in the transport collision avoidance. Products using moisture proof, dry, sealed packaging,

此规格书为东溢公司机密文件且涉及专利保护事宜,未经东溢公司书面签章确认同意严禁转载转发,此规格书中所有条款内容最终解释权归东溢公司所有, 特此声明! Hereby declared that this technical datasheet is a confidential document of Dongyi and involves patent protection matters, reproduction and forwarding without the written permission of Dongyi Company is strictly prohibited, the final interpretation of all the terms and conditions in this technical datasheet belongs to Dongyi.

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	<b>出厂检验报告</b> 客戶(customer):	编号: JL-Q-02-004-12 ,<70%RH保存3个月 ℃,70%RH for 3 months) 测试结果 (Test Result)
日期(Date):     品名(Material spec)       批号(Lot No.)     加诺(Lot No.)       补强板厚度(Stiffener thickness) Unit: μm        接着剂厚度(Adhesive thickness) Unit: μm        保存期限(Shelf life)        位验项目 (Test item)     位验方法 (Test method)       息厚度 (Total thickness)     东溢规范 (Unit: μm)       幅宽     东溢规范	客戶 (customer): <10℃ (Below 10 品质标准 (Quality Spec) 厚度≤100um,±5 厚度>100um,±10	c, <70%RH保存3个月 ℃,70%RH for 3 months) 测试结果
品名(Material spec)     批号 (Lot No.)       批号 (Lot No.)        补强板厚度(Stiffener thickness) Unit: µm        接着剂厚度(Adhesive thickness) Unit: µm        保存期限(Shelf life)        检验项目 (Test item)        協厚度 (Total thickness)        幅宽     东溢规范	<pre> &lt;10℃     ( Below 10)     品质标准     (Quality Spec)     厚度≤100um, ±5     厚度&gt;100um, ±10</pre>	C,70%RH for 3 months) 测试结果
批号(Lot No.)       补强板厚度(Stiffener thickness) Unit:μm       接着剂厚度(Adhesive thickness) Unit:μm       保存期限(Shelf life)       检验项目 (Test item)       危險方法 (Test item)       夏厚度     东溢规范 (Unit:μm)       幅宽     东溢规范	(Below 10 品质标准 (Quality Spec) 厚度≤100um,±5 厚度>100um,±10	C,70%RH for 3 months) 测试结果
接着剂厚度(Adhesive thickness) Unit:μm 保存期限(Shelf life) 检验项目 检验方法 (Test item) (Test method) 意厚度 东溢规范 (Total thickness) (Unit:μm) 幅宽 东溢规范	(Below 10 品质标准 (Quality Spec) 厚度≤100um,±5 厚度>100um,±10	C,70%RH for 3 months) 测试结果
保存期限(Shelf life)       检验项目 (Test item)     检验方法 (Test method)       总厚度 (Total thickness)     东溢规范 (Unit: µm)       幅宽     东溢规范	(Below 10 品质标准 (Quality Spec) 厚度≤100um,±5 厚度>100um,±10	C,70%RH for 3 months) 测试结果
<sup> </sup>	(Below 10 品质标准 (Quality Spec) 厚度≤100um,±5 厚度>100um,±10	C,70%RH for 3 months) 测试结果
(Test item)     (Test method)            意厚度         东溢规范         (Unit: μm)           」         「         「         「	(Quality Spec) 厚度≤100um,±5 厚度≥100um,±10	
(Total thickness) (Unit: μm) 」 幅宽 东溢规范	厚度>100um,±10	
	+2/-0	
剥离强度 (Peel Strength) (Unit:kgf/cm)	≧0.7	
巻曲 TD IPC-TM-650 2.4.22 (Curl) MD (Unit:cm)	≤5	
焊锡耐热性 Solder Float Resistance) IPC-TM-650 2.4.13 () 288℃/10sec	无分层起泡 No Blistering or Delamination )	
产品判定结果		XY Y
ż:	$\mathbf{C}$	
以上测试数据仅供参考(Above test data for reference on	ly)	
2.上述产品不含[RoHS]所规定的禁用物质(The chemical mater: 3.如产品被放置在低温下储存环境(尤其是冬季)建议客户在使 (20——30℃)后方才使用、以确保最佳产品使用特性,同时也/ The product should not be directly exposed to sunlight	电用前将产品静置回暖直至 应避免放置在阳光直接照 or stored at high tem	至产品温度回升至室温 射及高温环境下。
optimum operating temperature is between 20°C and 30°C.		
L.在有胶补强板贴合前,如接触界面做表面清洁,亦须保证接触		
Before use, ensure that the contact surface is dry and (such as acid, alkali, oil pollution, etc.).	d there are no residua.	I SOLVENTS
. 压合后的产品建议使用千层架烘烤,如无千层架建议叠层张数	你不超过20PNL,以避免鑫	层太多而影响产品
When heated, no more than 20 circuit boards are stacks	ed.	
址:广东省中山市南区昌盛路22号 电话: 0760-2333878	84 传真: 0760-23336	558 邮编: 528455
核(APPROED BY): 检验员(CHE	NYKED BY).	
	· A	



温度 Temp: 160~170℃; 时间 Time: 60~120min.

注 Note: 以上建议压合参数,鉴于各厂

家机台及生产工艺差异,故仅供参考。Customers can according to their own technology, equipment conditions and performance requirements, through the test to determine the appropriate operating conditions.

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### ● 使用注意事项 Matters needing attention

1. 如产品被放置在低于 10 度以下储存环境,建议客户在使用前将产品静置 4 小时 以上回暖直至产品温度回升至室温温度(20--30℃)后方才使用、以确保最佳产品 使用特性,同时也应避免放置在阳光直接照射及高温环境下。if product was placed in under Temperature 10℃ for storage, the product should be placed in the room temperature 20~30℃ more than 4 hours before using, in order to make the product temperature up to 20~30℃, to ensure the best product features. At the same time should also avoid placing it in direct sunlight and high temperature environment.

2. 在有胶补强板贴合前,如接触界面做表面清洁,亦须保证接触界面干燥及不残留 溶剂 (如酸碱、油污等)。With adhesive stiffener before laminating, such as the contact interface to do surface cleaning, also need to ensure that the contact interface is dry and not residual solvents (such as acid and alkali, oil, etc.).

3. 压合后的产品建议使用千层架烘烤,如无千层架建议叠层张数不超过 20PNL,以 避免叠层太多而影响产品固化效果。Pressing products recommend the use of multi-layer frame, such as no proposal for multi-layer frame lamination number no more than 20 PNL, to avoid the laminated too much and influence product curing effect.

 4. 此规格书中表述的所有测试数据以及建议之工艺条件和参数仅供参考,产品使用 方需要按照自身实际生产设备及产品要求等因素自行确认最优生产工艺及作业参数。特此声明!

Hereby declared that all test data and recommended process conditions and operating parameters presented in this technical datasheet are for informational purposes only. Product users need to confirm the optimal production process and operating parameters according to their actual production equipment and product requirements.

### ●常规物性测试方法 Properties Test Method

#### 剥离强度检验方法 Peel Test Method

1、范围The range:

本检验方法适用东溢公司有胶补强产品剥离强度之量测。The test method for stiffener measurement of peel strength.

2、 检测仪器 Testing instruments:

剥离强度测试仪。Peel strength testing instruments.

3、 样品制作 The sample:

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a) 将补强板裁切成10cm长,0.3-0.5cm宽试片,有胶一面与DSIF1201单面基材(ED铜)铜箔基板的PI面贴合。The stiffener is cut into 10cm long and 0.3-0.5cm wide, and the adhesive side is bonded to the PI surface of the DSIF1201 (ED copper).

b) 快压: 温度180℃、压力120kgf/cm2、预 热 时 间10sec、压 着 时 间120sec。Quick pressure: temperature 180℃, pressure 120 kgf/cm2, Time10 s, 120 s; c) 熟化: 160℃×60min。Cure: 160 ℃ x 60 min.

4、 样品测试 The sample test:

a) 取熟化过后之样片,烧开使得补强板与铜箔的 PI 面分开然后用手撕开 约 3cm。Take samples after curing, cutting 1 cm width to boil make PI is separated from copper foil.

b) 把覆铜面用双面胶固定在测试仪的滚轮上,用夹具夹住补强板的一端, 与滚轮垂直,然后匀速上升,每隔 1 秒,按打印机一次,共打印出 15~30 个数据即可,取打印数据的平均值作为此条样品的剥离强度值。The samples FCCL surface with double-sided adhesive fixed on the roller tester, fixture for clipping the copper foil at one end, and vertical roller, and then rising at a constant speed, every 1 second, print 1 data, print out together 15<sup>~</sup>30 data, take the print data as the average of the peel strength value of this sample.

c)注意事项: 剥离机上升速度: 50mm/min, 剥离距离: 10~20mm; 样品与 滚轮垂直。Note: machine rise: 50 mm/min, stripping distance: 10<sup>~</sup> 20 mm; Pull copper foil, samples and vertical roller.

5、公式计算 Formula to calculate:

拉力 Tensile force (kgf)

剥离强度 Peel strength =

宽度 The width (cm)

注: 以上测试方法参考 IPC-TM-650, Method 2.4.9; Note: The above specification reference IPC - TM - 650, Method 2.4.9.

#### 焊锡耐热性检验方法 Solder Resistance Test Method

1. 范围 The range:

本检验方法适用于东溢公司补强板产品焊锡耐热性之量测。The test

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method for stiffener measurement of solder resistance.

2. 检测设备 Testing instruments:

锡炉。Wave solder

3. 样品制作 The sample:

a) 将样片切成 10cm×10cm 大小, 与大小一致的 DSIF1201 单面基材 (ED 铜) PI 面贴合。The stiffener is cut into 10cm×10cm, and the adhesive side

is bonded to the PI surface of the  $\ensuremath{\mathsf{DSIF1201}}$  (ED copper).

b) 将样品平放在铜箔PI面上放入100℃过塑机过一遍。The sample placed into 100 ℃ in PI surface of copper foil presses over.

c) 快压: 温度 180±5℃、压力 120kgf/cm2(表压)、预热 10s、成型 120s; 熟化: 160 ℃ × 60min; Quick pressure: temperature 180℃, pressure 120 kgf/cm2, Time10 s, 120 s;Cure: 160 ℃ x 60 min.

d)将熟化完成的样品裁剪成剪取5±1cm × 5±1cm立即进行浸锡测试;如无 法立刻测试的,先将样品密封放置于干燥器中,在进行焊锡耐热性测试前, 先将试样放入空气循环烘箱,用135±10℃温度烘1小时,样品取出后立即进 行测试以免因受潮影响测试误判。Will complete the samples of the slaking tailoring shearing 5±1 cm x 5 ±1 cm immersion tin test immediately; As can't test at once, the first sample of the seal is placed in the dryer, before solder heat resistance test, the sample into the first air circulation drying oven, with 135 plus or minus 10 °C temperature bake for 1 hour, to take out the sample immediately after testing in order to avoid because of be affected with damp be affected with damp impact test miscalculation.

4. 样品测试The sample test:

用镊子夹住样品浸入恒温焊锡液中,焊锡液温度288±5℃,每个样品浸锡 10S,然后拿出观察其表面是否有分层或起泡。Using tweezers samples immersed in a constant temperature liquid solder, solder liquid temperature 288±5℃, each sample dipping 10S, then take out to observe the surface whether delamination or blistering.

注: 以上参考 IPC-TM-650, Method 2.4.13。 Note: The above specification reference IPC - TM - 650, Method 2.4.13.